504475751 07/27/2017

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

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EPAS ID: PAT4522453

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chun-Hao Lin	07/21/2017
Hsin-Yu Chen	07/21/2017
Shou-Wei Hsieh	07/21/2017

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.	
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park	
City:	Hsin-Chu City	
State/Country:	TAIWAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15660991

CORRESPONDENCE DATA

Fax Number: (703)997-4517

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ATTORNEY DOCKET NUMBER:	NAUP3064USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	07/27/2017

Total Attachments: 6

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PATENT REEL: 043107 FRAME: 0133

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PATENT REEL: 043107 FRAME: 0134

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

As the below named inventor, I here This declaration is directed to:	eby declare that:		
☑ The attached application, o	r		
☐ United States application no	umber	_filed on,	or
☐ PCT international application	on number	filed on	
The above-identified application was	s made or authorized to be made	by me.	
believe that I am the original inventage in believe that I am the original inventage in believe that I am the original inventage in the original inv	tor or an original joint inventor of a	a claimed invention in the	
hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impi	al false statement made in this decrisionment of not more than five (5	claration is punishable) years, or both.	
n consideration of the payment by	UNITED MICROELECTRON	NICS having a postal add	ress of
No.3, Li-Hsin Road 2, Science	e-Based Industrial Park, Hsi	in-Chu City 300, Taiwan,	R.O.C.
referred to as "ASSIGNEE"below) to acknowledged, andfor other good are	o I of the sum of One Dollar (\$ 1.0 nd valuable consideration.	00), the receipt of which is her	eby
hereby sell, assign and transfer to a the entire right, title and interest in a nvention as above-identified applica nvention by the above application o substitutes, or extensions thereof, an	nd to any and all improvements w ation and, in and to, all Letters Pat r any continuations, continuation-	rhich are disclosed in the tent to be obtained for said in-part, divisions, renewals	ΞE
hereby covenant that no assignment entered into which would conflict wit	nt, sale, agreement or encumbran h this assignment;	ice has been or will be made	or
further covenant that ASSIGNEE wand documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent and estify as to the same in any interfe	legal equivalents as may be rence. litigation proceeding	s
epresentatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne N WITNESS WHEREOF, I have he	olication, said invention and said L ecessary or desirable to carry out	etters Patent and said	signing)
Note: An application data sheet (PTC	O/SB/14 or equivalent), including	naming the entire	

Page 1 of 6

NPO#NAU-P3064-USA:0 CUST#UMCD-2017-0163

F#NPO-P0002E-US1201 DSB0-106U012698

Docket No NAUP3064USA

LEGAL NAI				
Inventor:	Chun-Hao Lin	Date:	JUL 2 1 2017	IUL 2 1 2017
Signature:	Chun-Haw	Lin		

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NPO#NAU-P3064-USA:0 CUST#UMCD-2017-0163

F#NPO-P0002E-US1201 DSB0-106U012698

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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☐ PCT international application	n number	file	d on	•
The above-identified application was	s made or authorized to be made	by me.		
I believe that I am the original inventage application.	or or an original joint inventor of	a claime	d invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	Il false statement made in this de isonment of not more than five (5	claration) years,	is punishable or both.	
In consideration of the payment by	UNITED MICROELECTROICORP.	NICS	having a postal add	dress of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hs	in-Chu	City 300, Taiwar	ı, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1.6 and valuable consideration.	00), the r	receipt of which is he	ereby
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.				
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbrar n this assignment;	nce has t	oeen or will be made	or
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, is maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	lication, said invention and said I cessary or desirable to carry out	Letters P	atent and said oses thereof.	signing)
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), including s form. Use this form for <u>each ad</u>	naming t ditional i	the entire oventor.	

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NPO#NAU-P3064-USA:0 F#NPO-P0002E-US1201 CUST#UMCD-2017-0163 DSB0-106U012698

Docket No NAUP3064USA

LLGAL NAI	WIE OF INVENTOR (ASSI	SNOR)			
Inventor:	Hsin-Yu Chen		Date:	JUL 2 1 2017	
Signature;	Man En	den			_

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NPO#NAU-P3064-USA:0 CUST#UMCD-2017-0163

F#NPÖ-P0002E-US1201 DSB0-106U012698

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

As the below named inventor, I here This declaration is directed to:	eby declare that:			
☑ The attached application, or	r			
☐ United States application nu	umber	filed on	, , c	or
☐ PCT international application	n number	filed on		
The above-identified application was	s made or authorized to be mad	de by me.		
l believe that I am the original invent application.	tor or an original joint inventor o	of a claimed inve	ntion in the	
hereby acknowledge that any willfuunder18 U.S.C. 1001 by fine or impr	Il false statement made in this or risonment of not more than five	declaration is pur (5) years, or bot	nishable h.	
n consideration of the payment by	UNITED MICROELECTRO	ONICS havii	ng a postal addre	ss of
No.3, Li-Hsin Road 2, Science	e-Based Industrial Park, H	lsin-Chu City	300, Taiwan, I	R.O.C
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good are	o I of the sum of One Dollar (\$ and valuable consideration.	1.00), the receip	t of which is here	by
hereby sell, assign and transfer to a the entire right, title and interest in a nvention as above-identified applica nvention by the above application o substitutes, or extensions thereof, an	nd to any and all improvements ation and, in and to, all Letters F r any continuations, continuatio	s which are discle Patent to be obta n-in-part, divisio	osed in the ined for said ns. renewals.	Ξ
hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbr h this assignment;	rance has been o	or will be made or	٢
further covenant that ASSIGNEE wand documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent an estify as to the same in any inte	nd legal equivale rference, litigatio	nts as may be	
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne N WITNESS WHEREOF, I have he	olication, said invention and said ecessary or desirable to carry of	d Letters Patent ut the proposes	and said	gning)
Note: An application data sheet (PT0 nventive entity, must accompany thi	O/SB/14 or equivalent), includin is form. Use this form for <u>each a</u>	ng naming the er additional invent	tire or.	

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NPO#NAU-P3064-USA:0 CUST#UMCD-2017-0163

F#NPO-P0002E-US1201 DSB0-106U012698

Docket No NAUP3064USA

LEGAL NAI	WE OF INVENTOR(ASSIGNOR)			
Inventor:	Shou-Wei Hsieh	Date:	JUL 2 1 2017	
Signature:	Shon-Wei Hsief			_

NPO#NAU-P3064-USA:0 CUST#UMCD-2017-0163

RECORDED: 07/27/2017

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F#NPO-P0002E-US1201 DSB0-106U012698

PATENT REEL: 043107 FRAME: 0140